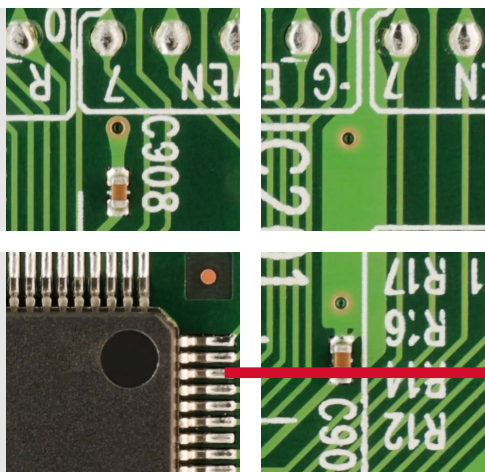


ORMECON CSN Classic

Immersion Tin



Trusted Reliability for When it Counts the Most.

ORMECON CSN Classic is a series of extremely stable immersion tin processes. Based on a patented predip, the ORMECON CSN tin processes are production-proven to reduce copper-tin diffusion speed by as much as 65% and provide superior shelf life. As a result, exceptional solderability and appearance, even after multiple lead-free assembly reflows, is achieved.

Each **ORMECON CSN Classic** process makes use of a nanometal layer that is deposited by the ORMECON predip. The predip catalyzes the tin deposition before the ORMECON immersion tin coating is applied. The resulting large tin grain structure significantly slows copper-tin intermetallic diffusion and provides the industry's longest shelf life. The predip makes the tin layer highly resistant to oxidation, while reducing copper diffusion and whisker formation by initiating a unique crystal structure.

Ideally suited for press fit technology, backplanes and fine pitch applications, **ORMECON CSN Classic** processes may be used with either MSA or sulfuric acid-based systems, providing the most flexible immersion tin plating systems on the market.

KEY FEATURES

- Production-proven industry leading automotive final finish
- Patented predip reduces copper-tin diffusion up to 65%
- Tolerates multiple lead-free assembly reflows
- Longest shelf life in the industry
- Unique crystal structure resists whisker formation

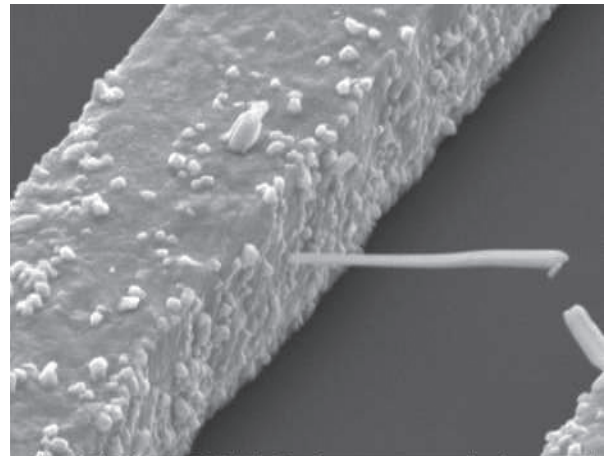
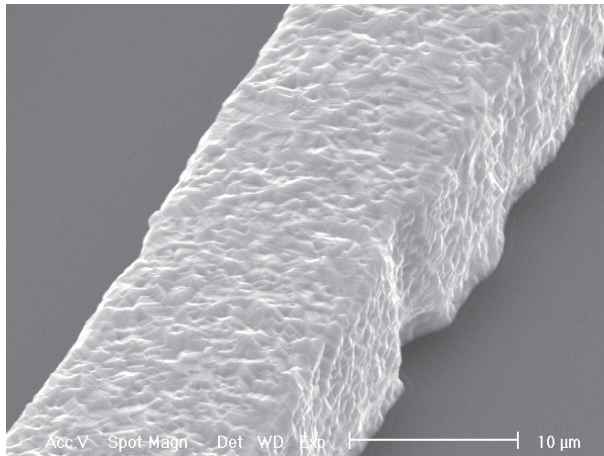
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The Competition Simply Can't Compete with ORMECON CSN Classic

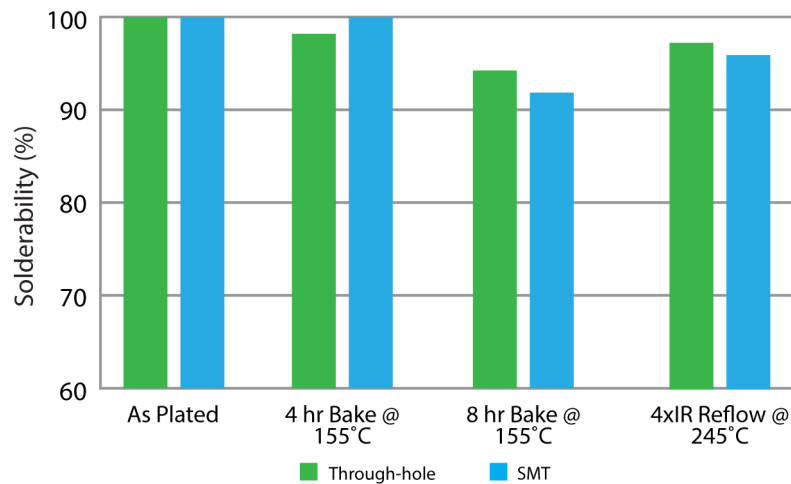
Ormecon CSNs patented prepip provides a mild barrier to diffusion of copper into the tin while also creating a unique low-stress grain structure which greatly reduces whisker formation.



LEFT: ORMECON CSN Classic's formulation prevents tin whisker formation and provides superior solderability.
RIGHT: Competitive tin process with solderability and whisker problems.

Unmatched Solderability After Lead Free Reflow

ORMECON CSN Solderability



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